

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT2659326

SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>JONG HOON KIM</td><td>12/06/2013</td></tr><tr><td>JAE HYUN SON</td><td>12/06/2013</td></tr><tr><td>BYOUNG DO LEE</td><td>12/06/2013</td></tr><tr><td>KUK JIN CHUN</td><td>11/13/2013</td></tr><tr><td>WOONG KYU CHOI</td><td>11/13/2013</td></tr></tbody></table>		Name	Execution Date	JONG HOON KIM	12/06/2013	JAE HYUN SON	12/06/2013	BYOUNG DO LEE	12/06/2013	KUK JIN CHUN	11/13/2013	WOONG KYU CHOI	11/13/2013
Name	Execution Date												
JONG HOON KIM	12/06/2013												
JAE HYUN SON	12/06/2013												
BYOUNG DO LEE	12/06/2013												
KUK JIN CHUN	11/13/2013												
WOONG KYU CHOI	11/13/2013												
RECEIVING PARTY DATA													
<table border="1"><tr><td>Name:</td><td>SK HYNIX INC.</td></tr><tr><td>Street Address:</td><td>2091, GYEONGCHUNG-DAERO, BUBAL-EUB</td></tr><tr><td>City:</td><td>ICHEON-SI GYEONGGI-DO</td></tr><tr><td>State/Country:</td><td>KOREA, REPUBLIC OF</td></tr></table>		Name:	SK HYNIX INC.	Street Address:	2091, GYEONGCHUNG-DAERO, BUBAL-EUB	City:	ICHEON-SI GYEONGGI-DO	State/Country:	KOREA, REPUBLIC OF				
Name:	SK HYNIX INC.												
Street Address:	2091, GYEONGCHUNG-DAERO, BUBAL-EUB												
City:	ICHEON-SI GYEONGGI-DO												
State/Country:	KOREA, REPUBLIC OF												
<table border="1"><tr><td>Name:</td><td>SNU R&DB FOUNDATION</td></tr><tr><td>Street Address:</td><td>1, GWANAK-RO, GWANAK-GU</td></tr><tr><td>City:</td><td>SEOUL</td></tr><tr><td>State/Country:</td><td>KOREA, REPUBLIC OF</td></tr></table>		Name:	SNU R&DB FOUNDATION	Street Address:	1, GWANAK-RO, GWANAK-GU	City:	SEOUL	State/Country:	KOREA, REPUBLIC OF				
Name:	SNU R&DB FOUNDATION												
Street Address:	1, GWANAK-RO, GWANAK-GU												
City:	SEOUL												
State/Country:	KOREA, REPUBLIC OF												
PROPERTY NUMBERS Total: 1													
<table border="1"><thead><tr><th>Property Type</th><th>Number</th></tr></thead><tbody><tr><td>Application Number:</td><td>14139249</td></tr></tbody></table>		Property Type	Number	Application Number:	14139249								
Property Type	Number												
Application Number:	14139249												
CORRESPONDENCE DATA													
Fax Number:	(630)908-7653												
Phone:	6309087652												
Email:	uspto.actions@wpapat.com												
<i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i>													
Correspondent Name:	WILLIAM PARK & ASSOCIATES PATENT LTD.												
Address Line 1:	930 N. YORK ROAD, SUITE 201												
Address Line 4:	HINSDALE, ILLINOIS 60521												

OP \$40.00 14139249

ATTORNEY DOCKET NUMBER:	PA1439-0
NAME OF SUBMITTER:	WOOCHOON WILLIAM PARK
Signature:	/Woochoon William Park/
Date:	12/23/2013
	This document serves as an Oath/Declaration (37 CFR 1.63).
Total Attachments: 3 source=PA1439-0_Decl_Assign#page1.tif source=PA1439-0_Decl_Assign#page2.tif source=PA1439-0_Decl_Assign#page3.tif	

**DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION
USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT**

Title of Invention	SEMICONDUCTOR CHIP AND STACKED TYPE SEMICONDUCTOR PACKAGE HAVING THE SAME
Declaration	<p>As the below named inventor(s), I hereby declare that: The declaration is directed to:</p> <p><input checked="" type="checkbox"/> The attached application, or <input type="checkbox"/> United States application or PCT international application number <u>PCT/KR#####</u> filed on _____.</p> <p>The above-identified application was made or authorized to be made by me. I believe that I am the original or an original joint inventor of a claimed invention in the application. I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years or both.</p>
Assignment	<p>NOW, THEREFORE, in consideration of the sum of one dollar (\$1), the receipt whereof is acknowledge, and other good and valuable consideration, I, by these presents do sell, assign and transfer unto said assignee(s)</p> <p align="center">SK hynix Inc. 2091, Gyeongchung-daero, Bubal-eub, Icheon-si, Gyeonggi-do, Korea and Seoul National University R&DB Foundation 1, Gwanak-ro, Gwanak-gu, Seoul, Korea</p> <p>and the heirs, successors, assigns and legal representatives of the assignee(s) the full and exclusive right to the said invention in the United States and in its territorial possessions and in any and all foreign countries any and all improvements thereof, the entire rights, title and interest in and to any and all Patents which may be granted therefore in the United States. I hereby authorize and request the Director of the U.S. Patent and Trademark Office to issue said United States Patent to said assignee(s), of the entire right, title, and interest in and to the same, for his sole use and for the use of his legal representatives, to the full end of the term for which said Patent may be granted, as fully and entirely as the same would have been held by me had this assignment and sale not been made.</p> <p>I agree promptly upon request of the assignee(s), its heirs, successors, assigns and legal representatives of the assignee(s) to communicate any facts known to it respecting the patent and the invention set forth therein, and to execute and deliver without further compensation any power of attorney, Assignment, application, whether original, continuation, divisional or reissue, or other papers that may be necessary.</p> <p>I hereby covenant that no assignment, sale agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.</p> <p>I further covenant that assignee(s) will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to me and will testify as to the same in any litigation related thereto and will promptly execute and deliver to assignee(s) or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the purposes thereof.</p>

**DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION
USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT**

Legal Name Of Inventor	Inventor Name (First Middle LAST):	Jong Hoon KIM
	Inventor Signature:	<i>Jong Hoon Kim</i>
	Date:	December 6, 2013

Legal Name Of Joint Inventor, If Any	Inventor Name (First Middle LAST):	Jae Hyun SON
	Inventor Signature:	<i>Jae Hyun Son</i>
	Date:	December 6, 2013

Legal Name Of Joint Inventor, If Any	Inventor Name (First Middle LAST):	Byeung Do LEE
	Inventor Signature:	<i>Byeung Do Lee</i>
	Date:	December 6, 2013

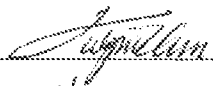
Legal Name Of Joint Inventor, If Any	Inventor Name (First Middle LAST):	
	Inventor Signature:	
	Date:	

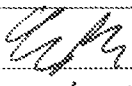
Legal Name Of Joint Inventor, If Any	Inventor Name (First Middle LAST):	
	Inventor Signature:	
	Date:	

Legal Name Of Joint Inventor, If Any	Inventor Name (First Middle LAST):	
	Inventor Signature:	
	Date:	

Legal Name Of Joint Inventor, If Any	Inventor Name (First Middle LAST):	
	Inventor Signature:	
	Date:	

DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION
USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

Legal Name Of Joint Inventor, If Any	Inventor Name (First Middle LAST):	Kukjin CHUN
	Inventor Signature:	
	Date:	NOV. 13, 2013

Legal Name Of Joint Inventor, If Any	Inventor Name (First Middle LAST):	Woongkyu CHOI
	Inventor Signature:	
	Date:	NOV. 13, 2013